

IR02H420

Features

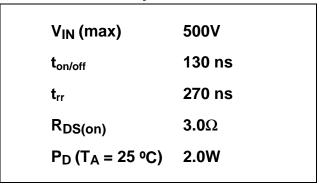
- Output Power MOSFETs in half-bridge configuration
- 500V Rated Breakdown Voltage
- High side gate drive designed for bootstrap operation
- Matched propagation delay for both channels
- Independent high and low side output channels
- Undervoltage lockout
- 5V Schmitt-triggered input logic
- Half-Bridge output out of phase with HIN

Description

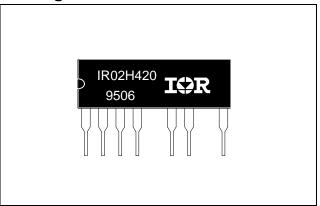
The IR02H420 is a high voltage, high speed half bridge. Proprietary HVIC and latch immune CMOS technologies, along with the HEXFET® power MOSFET technology, enable ruggedized single package construction. The logic inputs are compatible with standard CMOS or LSTTL outputs. The front end features an independent high and low side driver in phase with the logic compatible input signals. The output features two HEXFETs in a half-bridge configuration with a high pulse current buffer stage designed for minimum cross-conduction in the half-bridge. Propagation delays for the high and low side power MOSFETs are matched to simplify use. The device can operate up to 500 volts.

HIGH VOLTAGE HALF-BRIDGE

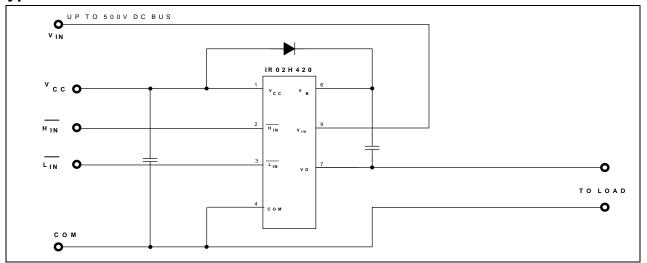
Product Summary



Package



Typical Connection





Absolute Maximum Ratings

Absolute Maximum Ratings indicate sustained limits beyond which damage to the device may occur. All voltage parameters are absolute voltages referenced to COM, all currents are defined positive into any lead. The Thermal Resistance and Power Dissipation ratings are measured under board mounted and still air conditions.

	Parameter			
Symbol	Definition	Min.	Max.	Units
V _{IN}	High Voltage Supply	-0.3	500	
V_B	High Side Floating Supply Absolute Voltage	-0.3	525	
VO	Half-Bridge Output Voltage	-0.3	$V_{IN} + 0.3$	V
eet4ViH/ViL	Logic Input Voltage (HIN & LIN)	-0.3	V _{CC} + 0.3	1
V _{CC}	Low Side and Logic Fixed Supply Voltage	-0.3	25	1
dv/dt	Peak Diode Recovery dv/dt		3.5	V/ns
P _D	Package Power Dissipation @ T _A ≤ +25°C		2.00	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient		60	°C/W
TJ	Junction Temperature	-55	150	
Ts	Storage Temperature	-55	150	۰C
TL	Lead Temperature (Soldering, 10 seconds)		300]

Recommended Operating Conditions

The Input/Output logic timing diagram is shown in Figure 1. For proper operation the device should be used within the recommended conditions.

	Parameter			
Symbol	Definition	Min.	Max.	Units
V _B	High Side Floating Supply Absolute Voltage	VO + 10	VO + 20	
V_{IN}	High Voltage Supply		500	V
VO	Half-Bridge Output Voltage	(note 1)	500	
V _{CC}	Low Side and Logic Fixed Supply Voltage	10	20	
V _{IH} /V _{IL}	Logic Input Voltage (HIN & LIN)	0	V _{CC}	
I _D	Continuous Drain Current (T _A = 25°C)		0.7	Α
	$(T_A = 85^{\circ}C)$		0.5	
T _A	Ambient Temperature	-40	125	٥C

Note 1: Logic operational for VO of -5 to 500 V. Logic state held for VO of -5 to - V_B.



Dynamic Electrical Characteristics

 V_{BIAS} (V_{CC}, V_B) = 15V and T_A = 25°C unless otherwise specified. Switching time waveform definitions are shown in figure 2.

	Parameter	T,	A = 25°C	2		
Symbol	Definition	Min.	Тур.	Max.	Units	Test Conditions
t _{on}	Turn-On Propagation Delay (see note 2)		130	200		V _S = 0 V
t _{off}	Turn-Off Propagation Delay (see note 2)		90	200		$V_{S} = 500 \text{ V}$
t _r	Turn-On Rise Time (see note 2)		80	120	ns	
t _f	Turn-Off Fall Time (see note 2)		40	70		
MT	Delay Matching, HS & LS Turn-On/Off		30			
t _{rr}	Reverse Recovery Time (MOSFET Body Diode)		260			I _F = 0.7 A
Qrr	Reverse Recovery Charge (MOSFET Body Diode)		0.7		μC	$di/dt = 100A/\mu s$

Note 2: Switching times as specified and illustrated in figure 2 are referenced to the MOSFET gate input voltage. This is shown as HO in figure 2.

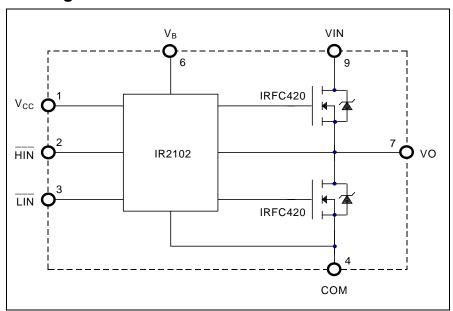
Static Electrical Characteristics

 V_{BIAS} (V_{CC}, V_{B}) = 15V and T_{A} = 25°C unless otherwise specified. The Input voltage and current levels are referenced to COM.

Parameter		T.	$T_A = 25^{\circ}C$			
Symbol	Definition	Min.	Тур.	Max.	Units	Test Conditions
Supply (Characteristics					
V _{CCUV+}	V _{CC} Supply Undervoltage Positive Going Threshold	8.8	9.3	9.8	V	
V _{CCUV} -	V _{CC} Supply Undervoltage Negative Going Threshold	7.5	8.2	8.6		
I _{QCC}	Quiescent V _{CC} Supply Current		140	240		
I _{QBS}	Quiescent V _{BS} Supply Current		20	50	μA	
Ios	Offset Supply Leakage Current			50		$V_{B} = V_{S} = 500V$
Input Ch	naracteristics					
V_{IH}	Logic "1" Input Voltage	2.7			V	$V_{CC} = 10V \text{ to } 20V$
V_{IL}	Logic "0" Input Voltage			0.8		
I _{IN+}	Logic "1" Input Bias Current		20	40	μA	
I _{IN-}	Logic "0" Input Bias Current			1.0	μA	
Output Characteristics						
R _{DS(on)}	Static Drain-to-Source On-Resistance		3.0		Ω	$I_D = 700 \text{mA}$
V_{SD}	Diode Forward Voltage		0.8		V	T _j = 150 °C



Functional Block Diagram

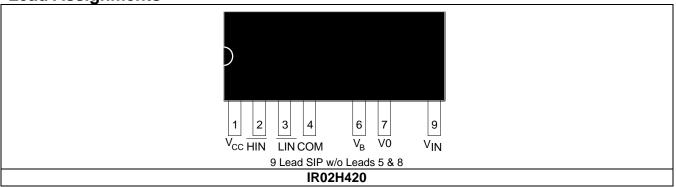


vw.DataSHEEt4U.COIII

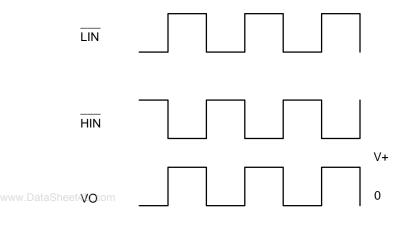
Lead Definitions

Lead			
Symbol	Description		
V _{CC}	Logic and internal gate drive supply voltage.		
HIN	Logic input for high side Half Bridge output, out of phase		
LIN	Logic input for low side Half Bridge output, in phase		
V _B	High side gate drive floating supply. For bootstrap operation a high voltage fast recovery diode is needed to feed from V_{CC} to V_{B} .		
V_{IN}	High voltage supply.		
VO	Half-Bridge output.		
COM	Logic and low side of Half-Bridge return.		

Lead Assignments



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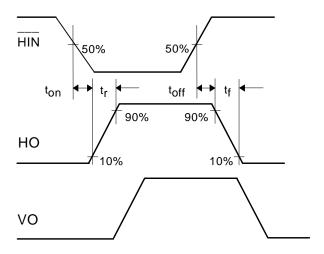


Figure 1. Input/Output Timing Diagram

Figure 2. Switching Time Waveform Definitions

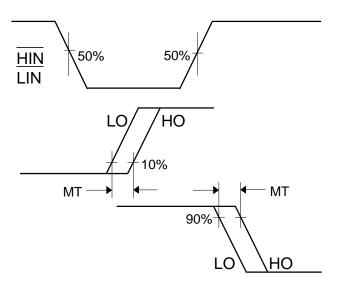
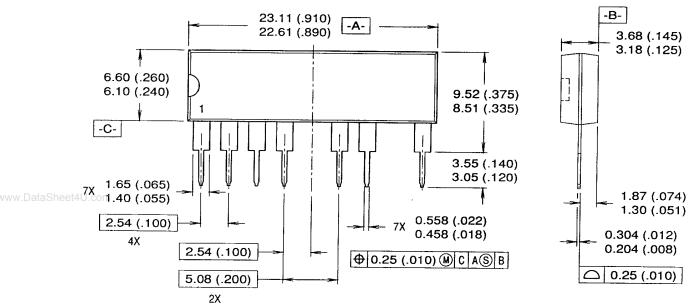


Figure 3. Delay Matching Waveform Definitions

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NOTES:

- 1. DIMENSIONING & TOLERANCING PER ANSI Y14.5M-1982.
- 2. CONTROLLING DIMENSION: INCH.
- 3. DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).

Package Outline



WORLD HEADQUARTERS: 233 KANSAS ST., EL SEGUNDO, CA 90245 USA • (310)322-3331 • FAX (310)322-3332 • TELEX 472-0403 EUROPEAN HEADQUARTERS: HURST GREEN, OXTED, SURREY RH8 9BB, UK • (44)0883 713215 • FAX (944)0883 714234 • TELEX 95219

Sales Offices, Agents and Distributors in Major Cities Throughout the World.

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